



Sheet 1 of 1

Form 1449*	Atty. Docket No.: 303.610US1	Serial No. 09/382,524
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Applicant: Paul A. Farrar	
	Filing Date: August 25, 1999	Group: Unknown

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**Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
PS	5,470,802	11/28/1995	Gnade, B.E., et al.	437	238	05/20/94
	5,473,814	12/12/1995	White, L.H.	29	840	01/07/94
	5,747,880	05/05/1998	Havemann, R.H., et al.	257	759	11/18/96
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**Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation Yes   No
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PS	1	Chiniwalla, N., et al., "Structure-Property Relations for Polynorbornenes", <u>Proceedings from the Eighth Meeting of the Dupont Symposium on Polymides In Microelectronics</u> , pp. 615-642, (1998)	✓
	1	Jayaraj, K., et al., "Low Dielectric Constant Microcellular Foams", <u>Proceedings from the Seventh Meeting of the DuPont Symposium on Polymides in Microelectronics</u> , pp. 474-501, (September 1996)	✓
	1	Miller, R.D., et al., "Low Dielectric Constant Polyimides and Polyimide Nanofoams", <u>Seventh Meeting of the DuPont Symposium on Polymides in Microelectronics</u> , pp. 443-473, (September 1996)	✓
	1	Shibasaki, T., et al., "Process and Application of Fumed Silica AEROSIL", <u>3rd Annual Workshop on Mechanical Polishing</u> , Lake Placid, New York, pp. 1-27, (1998)	✓
	1	Ting, C.H., "Low K Material/Process Development", <u>1996 VLSI Multilevel Interconnection State-of-the-Art Seminar</u> , pp. 171-212, (June 1996)	✓
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Applicant: Paul A. Farrar

Filing Date: August 25, 1999

Group: 2813

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**Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
PN	5,227,103	07/13/1993	Muschiatti, L.C.	264	45.9	02/27/92
J	5,591,676	01/07/1997	Hughes, et al.	437	195	03/16/95
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J	1	"ACCUSPIN T-18 Flowable Spin-On Polymer (SOP)", AlliedSignal - Advanced Microelectronic Materials, Sunnyvale, CA, pp. 1-2, (7/98)
J	1	Conti, R., et al., "Processing Methods to Fill High Aspect Ratio Gaps Without Premature Constriction", 1999 Proceedings of Dielectrics for Multilevel Interconnection Conference, pp. 201-209, (1999) ✓
J	1	Craig, J.D., "Polyimide Coatings", In: Packaging, Electronic Materials Handbook, Vol. 1, ASM International Handbook Committee (eds.), ASM International, Materials Park, OH, 767-772, (1989) ✓
J	1	Remenar, J., et al., "Templating Nanopores into Poly (Methylsilsesquioxane): New-Low Dielectric Coatings Suitable for Microelectronic Applications", Materials Research Society Symposium Proceedings, 511, pp. 69-74, (1998) ✓
J	1	Volksen, W., et al., "Characterization and Processing Considerations for Methylsilsesquioxane Based Dielectrics", Proceedings of the Fifth Dielectric for ULSI Multilevel Interconnections, Santa Clara, CA, pp. 83-90, (1999) ✓

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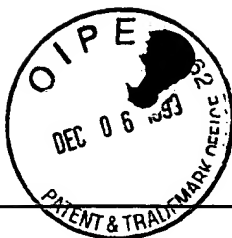
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	Filing Date: August 25, 1999	Group: 2812

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Pd	3,953,566	04/27/1976	Gore, R.W.	264	288	07/03/73
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	4,096,227	06/20/1978	Gore, R.W.	264	210R	12/03/75
	4,482,516	11/13/1984	Bowman, J.B., et al.	264	127	09/10/12
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